L Number	Hits	Search Text	DB	Time stamp
1	477	(leadframe (lead adj frame)) and ((die adj pad) (mounting adj (pad portion region area))) and (loc (lead adj1 chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/15 08:35
2	312	((leadframe (lead adj frame)) and ((die adj pad) (mounting adj (pad portion region area))) and (loc (lead adj1 chip))) and ((sealing adj resin) encapsula$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/15 08:36
3	88	(((leadframe (lead adj frame)) and ((die adj pad) (mounting adj (pad portion region area))) and (loc (lead adj1 chip))) and ((sealing adj resin) encapsula$4)) and ((tie connect$3) adj bar)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/15 08:38
—	0	("(leadframe (lead adj frame)) and ((die adj pad) (mounting adj (pad portion region area))) and (loc (lead adj1 chip))").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/10/22 13:21
—	303	(leadframe (lead adj frame)) and ((die adj pad) (mounting adj (pad portion region area))) and (loc (lead adj1 chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/15 08:35
—	117	((leadframe (lead adj frame)) and ((die adj pad) (mounting adj (pad portion region area))) and (loc (lead adj1 chip))) not (((leadframe (lead adj frame)) and ((die adj pad) (mounting adj (pad portion region area))) and (loc (lead adj1 chip))) and ((sealing adj resin) encapsula$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/15 08:36
—	31	(leadframe (lead adj frame)) and (dummy near lead) and (loc (lead adj1 chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/29 12:57
—	10146	(loc (lead adj1 chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/15 10:47
—	740	((loc (lead adj1 chip))) and (encapsulating encapsualted encapsualate (sealing adj resin) (molding adj compound))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/12/15 08:37
—	322	(((loc (lead adj1 chip))) and (encapsulating encapsualted encapsualate (sealing adj resin) (molding adj compound))) and (bending bent bend)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/15 10:51
—	317	((((loc (lead adj1 chip))) and (encapsulating encapsualted encapsualate (sealing adj resin) (molding adj compound))) and (bending bent bend)) and (adhesive glue bonding bonded bond)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/12 09:07
—	153	((loc (lead adj1 chip))) and disturbing	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/12 09:32
—	0	((loc (lead adj1 chip))) and (disturbing near plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/12 09:32
—	5	(((loc (lead adj1 chip))) and (encapsulating encapsualted encapsualate (sealing adj resin) (molding adj compound))) and disturbing	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/12 09:32
—	1	5932923.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/13 06:48
—	0	6153923.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/13 06:58

—	0	6153923.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/13 06:58
—	1	5932923.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/13 06:58
—	3	5897339.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/13 07:33
—	1	5530286.pn. and epoxy	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/13 09:08
—	1	5932923.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/13 07:53
—	26	5535509.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/13 07:59
—	0	6291273.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/13 08:02
—	0	6291273.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/13 08:02
—	1	5530286.pn. and polyimide	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/13 09:40
—	636	257/667	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/13 09:40
—	96	257/667 and (encapsulating encapsualted encapsualate (sealing adj resin) (molding adj compound)) and (bending bent bend)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/13 12:19
—	11	"09/449,834" and "Nikkei Microdevice"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/11/13 12:21
—	222	((leadframe (lead adj frame)) and ((die adj pad) (mounting adj (pad portion region area))) and (loc (lead adj1 chip))) and ((sealing adj resin) encapsula$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/29 12:56
—	6	(((leadframe (lead adj frame)) and ((die adj pad) (mounting adj (pad portion region area))) and (loc (lead adj1 chip))) and ((sealing adj resin) encapsula$4)) and (dummy near lead)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/29 12:59
—	75	(((leadframe (lead adj frame)) and ((die adj pad) (mounting adj (pad portion region area))) and (loc (lead adj1 chip))) and ((sealing adj resin) encapsula$4)) and ((bent bend bending) near3 lead)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/29 13:00

-	73	(((((leadframe (lead adj frame)) and ((die adj pad) (mounting adj (pad portion region area))) and (loc (lead adj1 chip))) and ((sealing adj resin) encapsula$4)) and ((bent bend bending) near3 lead)) not ((((leadframe (lead adj frame)) and ((die adj pad) (mounting adj (pad portion region area))) and (loc (lead adj1 chip))) and ((sealing adj resin) encapsula$4)) and (dummy near lead))	USPAT; US-PGPUB; ·EPO; JPO; DERWENT	2002/04/29 13:00
-	8	(((leadframe (lead adj frame)) and ((die adj pad) (mounting adj (pad portion region area))) and (loc (lead adj1 chip))) and ((sealing adj resin) encapsula$4)) and ((bent bend bending) near3 (inner near lead))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/29 13:01
-	8	((((leadframe (lead adj frame)) and ((die adj pad) (mounting adj (pad portion region area))) and (loc (lead adj1 chip))) and ((sealing adj resin) encapsula$4)) and ((bent bend bending) near3 (inner near lead))) not ((((leadframe (lead adj frame)) and ((die adj pad) (mounting adj (pad portion region area))) and (loc (lead adj1 chip))) and ((sealing adj resin) encapsula$4)) and (dummy near lead))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/29 13:01
-	10727	(loc (lead adj1 chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/10 08:22
-	149	((loc (lead adj1 chip))) and (flat near1 package)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/10 08:23
-	83	(((loc (lead adj1 chip))) and (flat near1 package)) and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/10 08:25
-	71	((((loc (lead adj1 chip))) and (flat near1 package)) and solder) and (substrate pcb (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/10 08:26
-	54	(((((loc (lead adj1 chip))) and (flat near1 package)) and solder) and (substrate pcb (printed adj circuit adj board))) and (resin encapsulant sealing)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/10 08:26
-	84	(((loc (lead adj1 chip))) and (flat near1 package)) and (solder (bonding adj material))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/10 08:25
-	72	((((loc (lead adj1 chip))) and (flat near1 package)) and (solder (bonding adj material))) and (substrate pcb (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/10 08:26
-	55	(((((loc (lead adj1 chip))) and (flat near1 package)) and (solder (bonding adj material))) and (substrate pcb (printed adj circuit adj board))) and (resin encapsulant sealing)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/10 08:29
-	4	5998866.URPN.	USPAT	2002/06/03 07:25
-	1	6258624.URPN.	USPAT	2002/06/03 07:26
-	24	("Re36613" | "5214307" | "5220195" | "5291059" | "5365107" | "5437915" | "5442231" | "5498901" | "5594234" | "5637915" | "5638596" | "5767560" | "5767572" | "5770479" | "5814877" | "5905299" | "5920114" | "5998866" | "6002165" | "6043430" | "6049125" | "6068180" | "6075283" | "6078099").PN.	USPAT	2002/06/03 07:26
-	2	6078099.URPN.	USPAT	2002/06/03 07:27
-	2	("5172214" | "5291059").PN.	USPAT	2002/06/03 07:27

–	4	6068180.URPN.	USPAT	2002/06/03 07:29
–	21	("Re36613" | "5214307" | "5220195" | "5291059" | "5365107" | "5437915" | "5442231" | "5498901" | "5594234" | "5637915" | "5638596" | "5767570" | "5767572" | "5770479" | "5920114" | "5998866" | "6002165" | "6043430" | "6049125" | "6068180" | "6075283").PN.	USPAT	2002/06/03 07:30
–	4	5998866.URPN.	USPAT	2002/06/03 07:32
–	9	("4766478" | "5041696" | "5291059" | "5440170" | "5606198" | "5757066" | "5776802" | "5783861" | "5821628").PN.	USPAT	2002/06/03 07:32
–	10849	(loc (lead adj1 chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/15 10:47
–	474	((loc (lead adj1 chip))) and (inner adj lead) and (outer adj lead)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/15 10:52
–	4339	lead near2 width	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/15 10:52
–	76	(((loc (lead adj1 chip))) and (inner adj lead) and (outer adj lead)) and (lead near2 width)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/15 10:52
–	406	(((loc (lead adj1 chip))) and (inner adj lead) and (outer adj lead)) and (wire wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/15 10:58
–	280	((((loc (lead adj1 chip))) and (inner adj lead) and (outer adj lead)) and (wire wiring)) and (width length)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/15 10:58
–	183	(((((loc (lead adj1 chip))) and (inner adj lead) and (outer adj lead)) and (wire wiring)) and (width length)) and (bond$3 adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/15 10:59
–	238	(((((loc (lead adj1 chip))) and (inner adj lead) and (outer adj lead)) and (wire wiring)) and (width length)) and ((bond$3 adj pad) electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/15 10:59
–	5	"5933708"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/09/19 10:53
–	2	"6211573"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/09/19 10:53
–	7	"5933708" "6211573"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/09/19 10:53
–	0	6211573.URPN.	USPAT	2002/09/19 10:54
–	6	("5072280" | "5334803" | "5428247" | "5548160" | "5612569" | "5834837").PN.	USPAT	2002/09/19 10:54
–	0	6211573.URPN.	USPAT	2002/09/19 12:50
–	3	5933708.URPN.	USPAT	2002/09/19 12:50
–	1	"5286679".PN.	USPAT	2002/09/19 12:50